

Description

The μ PD4361B is a 65,536-word by 1-bit static RAM fabricated with advanced silicon-gate technology. CMOS peripheral circuits and N-channel memory cells with polysilicon resistors make the μ PD4361B a high-speed device that requires very low power and no clock or refreshing.

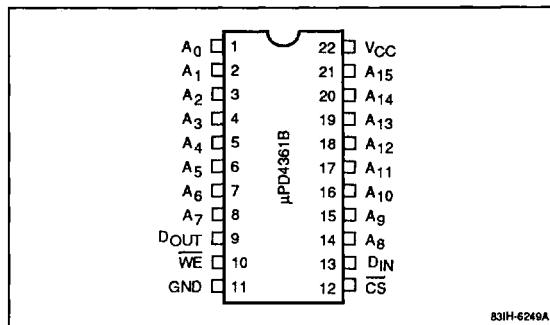
The device is packaged in a 22-pin plastic DIP and 24-pin plastic SOJ and has two types of access times, address and chip select.

Features

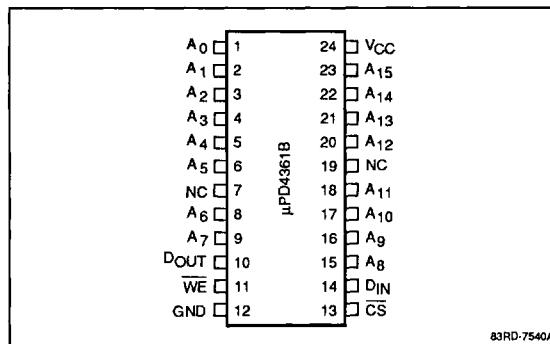
- 65,536 x 1-bit organization
- Single +5-volt power supply
- Fully static operation—no clock or refreshing
- TTL-compatible inputs and outputs
- Separated data input and output
- Three-state outputs
- Standard 22-pin plastic DIP and 24-pin plastic SOJ

Ordering Information

Part Number	Access Time (max)	Package
μ PD4361BCR-12	12 ns	22-pin plastic DIP
CR-15	15 ns	
CR-20	20 ns	
μ PD4361BLA-12	12 ns	24-pin plastic SOJ
LA-15	15 ns	
LA-20	20 ns	

Pin Configurations**22-Pin Plastic DIP**

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24-Pin Plastic SOJ**Pin Identification**

Symbol	Function
A ₀ - A ₁₅	Address inputs
D _{IN}	Data input
D _{OUT}	Data output
CS	Chip select
WE	Write enable
GND	Ground
V _{CC}	+ 5-volt power supply

Absolute Maximum Ratings

Supply voltage, V_{CC}	- 0.5 to + 7.0 V
Input voltage output voltage, V_{IN} (Note 1)	- 0.5 to V_{CC} + 0.5 V
Operating temperature, T_{OPR}	0 to + 70°C
Storage temperature, T_{STG}	- 55 to + 125°C
Power dissipation, P_D	1.0 W

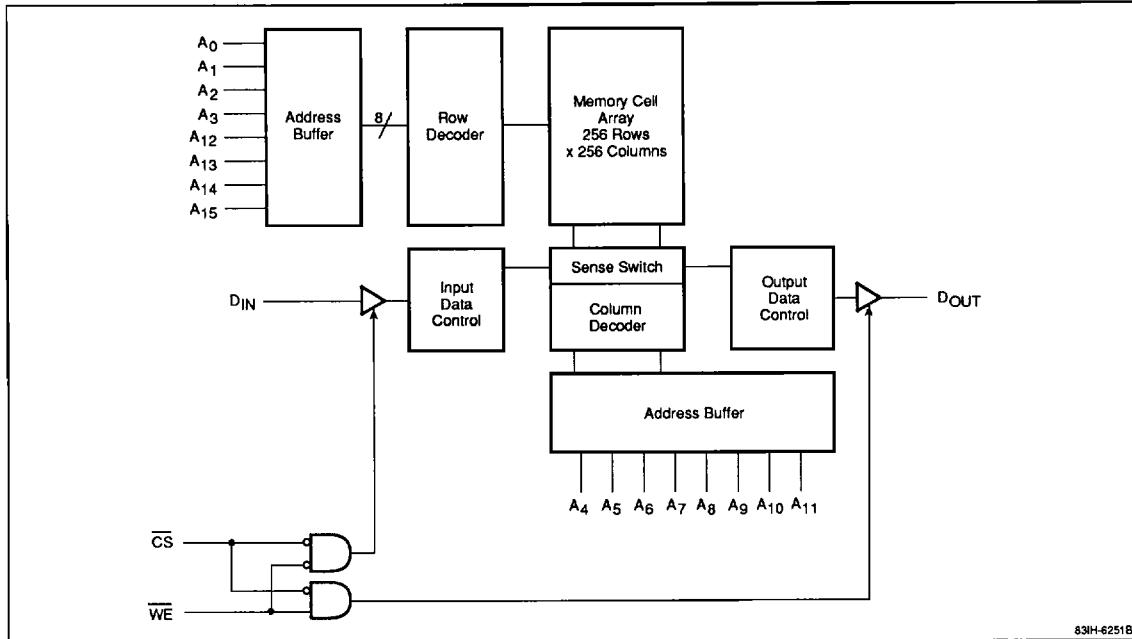
Exposure to Absolute Maximum Ratings for extended periods may affect device reliability; exceeding the ratings could cause permanent damage. The device should be operated within the limits specified under DC and AC Characteristics.

Notes:

(1) $V_{IN} = -3.0$ V minimum for 10 ns maximum pulse.

Truth Table

Function	\overline{CS}	\overline{WE}	Input/Output	I_{CC}
Not selected	H	X	High-Z	Standby
Read	L	H	D _{OUT}	Active
Write	L	L	High-Z	Active

Block Diagram**Recommended Operating Conditions**

Parameter	Symbol	Min	Typ	Max	Unit
Supply voltage	V_{CC}	4.5	5.0	5.5	V
Input voltage, high	V_{IH}	2.2		V_{CC} + 0.3	V
Input voltage, low	V_{IL}	- 0.5		0.8	V
Operating temperature	T_A	0		70	°C

Notes:

(1) $V_{IL} = -3.0$ V minimum for 10 ns maximum pulse.

Capacitance

$T_A = 25^\circ\text{C}$; $f = 1$ MHz; V_{IN} and $V_{OUT} = 0$ V (Note 1)

Parameter	Symbol	Min	Typ	Max	Unit
Input capacitance	C_{IN}		6		pF
Output capacitance	C_{DOUT}		8		pF

Notes:

(1) This parameter is sampled and not 100% tested.

DC Characteristics $T_A = 0 \text{ to } +70^\circ\text{C}; V_{CC} = +5.0 \text{ V } \pm 10\%$

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions
Input leakage current	I_{IL}	-2		2	μA	$V_{IN} = 0 \text{ V to } V_{CC}$
Output leakage current	I_{OL}	-2		2	μA	$V_{OUT} = 0 \text{ V to } V_{CC}; \overline{CS} = V_{IH}$
Standby supply current	I_{SB}			20	mA	$\overline{CS} = V_{IH}$
	I_{SB1}			2	mA	$\overline{CS} \geq V_{CC} - 0.2 \text{ V}; V_{IN} \leq 0.2 \text{ V or } \geq V_{CC} - 0.2 \text{ V}$
Output voltage, low	V_{OL}			0.4	V	$I_{OL} = 8.0 \text{ mA}$
Output voltage, high	V_{OH}	2.4			V	$I_{OH} = -4.0 \text{ mA}$

AC Characteristics $T_A = 0 \text{ to } +70^\circ\text{C}; V_{CC} = +5.0 \text{ V } \pm 10\%$

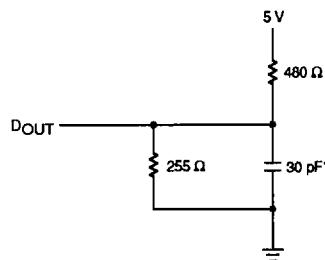
Parameter	Symbol	μ PD4361B-12		μ PD4361B-15		μ PD4361B-20		Unit	Test Conditions
		Min	Max	Min	Max	Min	Max		
<i>Read Operation</i>									
Operating supply current	I_{CC}		130		120		110	mA	$\overline{CS} = V_{IL}; I_{DOUT} = 0 \text{ mA}$
Read cycle time	t_{RC}	12		15		20		ns	(Note 2)
Address access time	t_{AA}		12		15		20	ns	
Chip select access time	t_{ACS}		12		15		20	ns	
Output hold from address change	t_{OH}	2		3		3		ns	
Chip select to output in low-Z	t_{LZ}	2		3		3		ns	(Note 3)
Chip deselect to output in high-Z	t_{HZ}	0	7	0	7	0	8	ns	(Note 4)
Chip select to power-up time	t_{PU}	0		0		0		ns	
Chip deselect to power-down time	t_{PD}	0	7	0	8	0	15	ns	
<i>Write Operation</i>									
Write cycle time	t_{WC}	12		15		20		ns	(Note 2)
Chip select to end of write	t_{CW}	11		13		15		ns	
Address valid to end of write	t_{AW}	11		13		15		ns	
Address setup time	t_{AS}	0		0		0		ns	
Write pulse width	t_{WP}	10		12		14		ns	
Write recovery time	t_{WR}	0		0		0		ns	
Data valid to end of write	t_{DW}	7		7		8		ns	
Data hold time	t_{DH}	0		0		0		ns	
Write enable to output in high-Z	t_{WZ}	0	7	0	7	0	8	ns	(Note 4)
Output active from end of write	t_{OW}	0		0		0		ns	(Note 3)

Notes:

- (1) Input pulse levels = GND to 3.0 V; input pulse rise and fall times = 5 ns; timing reference levels = 1.5 V; see figures 1 and 2 for output load.
- (2) All read cycle timings are referenced from the last valid address to the first transitioning address.

- (3) Transition is measured at $\pm 200 \text{ mV}$ from steady-state voltage with the loading shown in figure 2.
- (4) Transition is measured at $V_{OL} + 200 \text{ mV}$ and $V_{OH} - 200 \text{ mV}$ with the loading shown in figure 2.

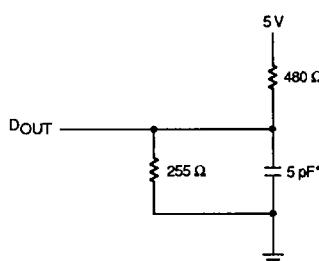
Figure 1. Output Load



*Including Scope and Jig

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Figure 2. Output Load for t_{HZ} , t_{LZ} , t_{WZ} , and t_{OW}

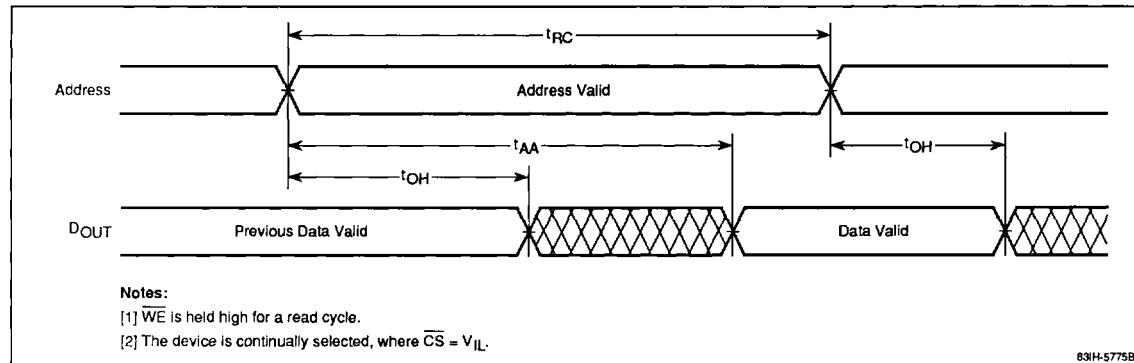


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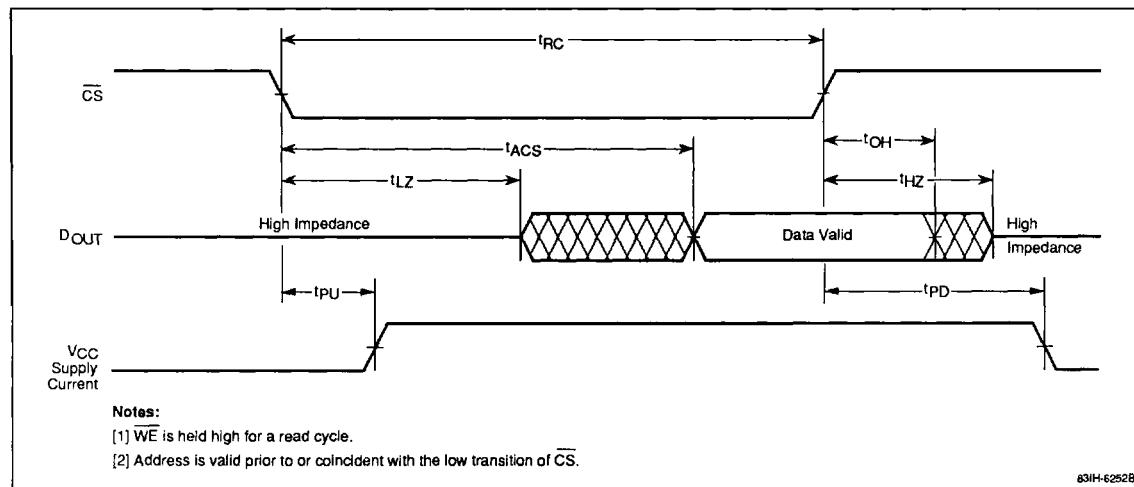
Timing Waveforms

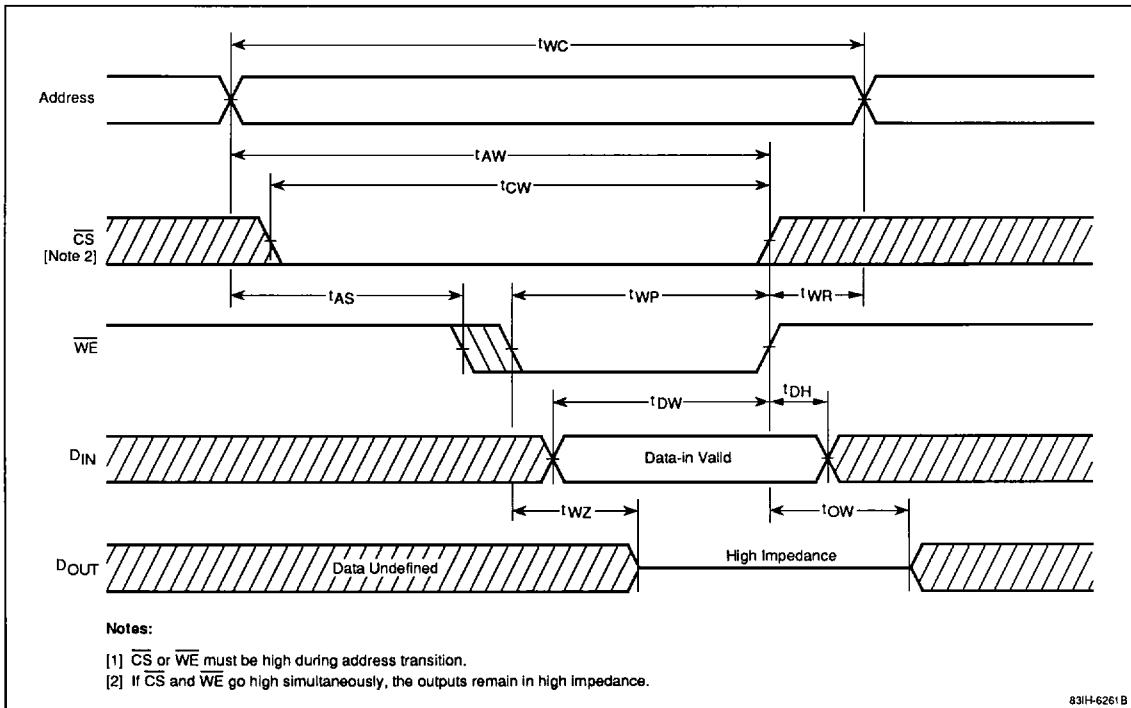
Address Access Cycle



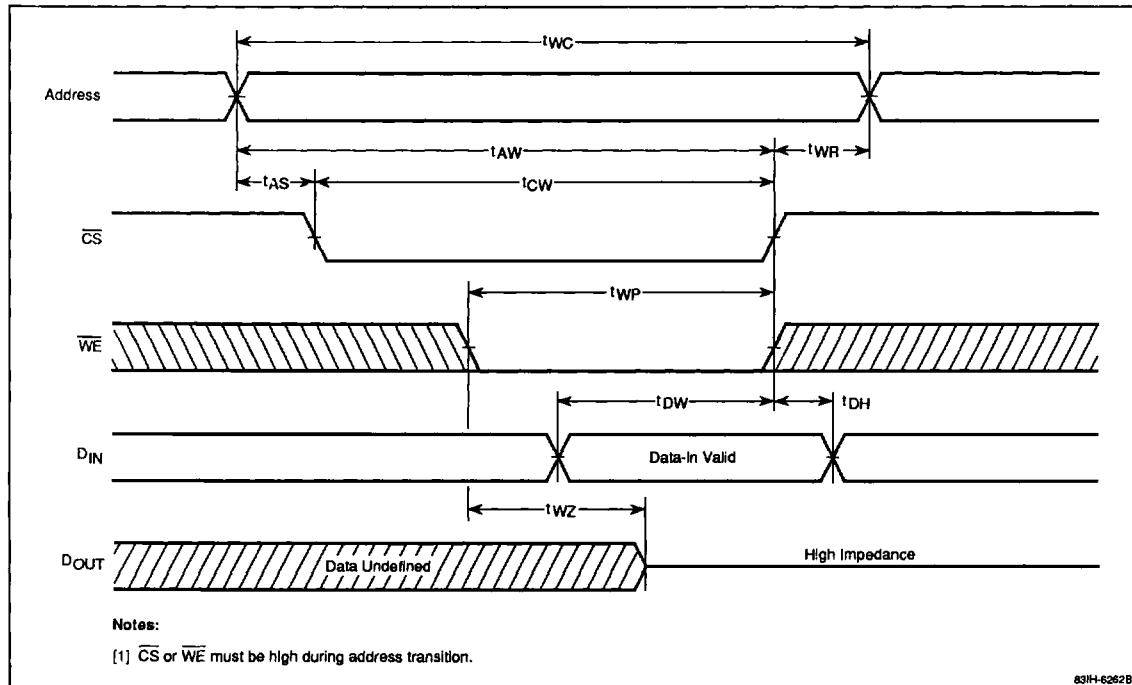
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Chip Select Access Cycle



Timing Waveforms (cont)***WE-Controlled Write Cycle***

Timing Waveforms (cont)

 \overline{CS} -Controlled Write Cycle

NEC

μPD4361B
